Specification of Thermoelectric Module

TEFC1-03520P

Description

The 35 couples, 6 mm \times 12/14 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70°C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

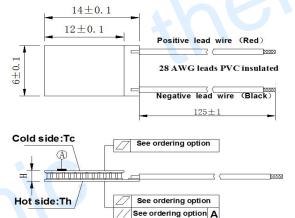
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	4.46	4.85	Voltage applied to the module at DT _{max}	
I _{max} (amps)	2.16	2.16	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	5.95	6.39	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (ohms)	1.55	1.70	The module resistance is tested under AC	
Tolerance (%)	10%		For thermal and electricity parameters	

A. Solder:

B. Sealant:

Geometric Characteristics Dimensions in millimeters



Ordering Option

Manufacturing Options

- C. Ceramics:
- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)
- **D.** Ceramics Surface Options:
- 1. Blank ceramics (not metallized)
- 2. Metallized (Au/Ni plating)
- 4. Customer specify sealing **X**.

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. SS: Silicone sealant

3. EPS: Epoxy sealant

2. T200: CuSn (Tmelt = 227 °C)

Standard ceramic surface without metallizing M1: Cold Side metallizingM2: Hot Side metalizing M3: Both Sides metallizing

M3: Both Sides metallizing

Naming for the Module

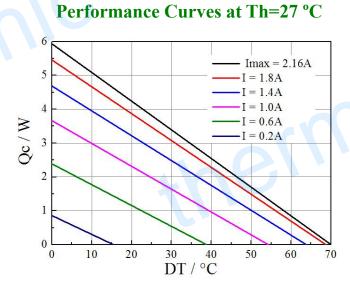
				i fulling for the mount
Suffix	Thickness	Flatness/	Lead wire length(mm)	TEFC1-03520PX- x - x - x - x
	H (mm)	Parallelism (mm)	Standard/Optional length	Ceramics
TF	0:2.3±0.1	0: 0.1/0.13	125±1/Specify	Flatness/ Parallelism
TF	1:2.3±0.05	1: 0.08/0.1	125±1/Specify	Solder
TF	2:2.3±0.025	2: 0.05/0.08	125±1/Specify	TEFC1-03520PM3-T100-NS-TF11-AIO-Au T100: BiSn(Tmelt=138°C)
Eg. TF11: Thickness (Without plating)2.3± 0.05 (mm) and Flatness 0.08				NS: No sealing AlO: Alumina (Al2O3, white 96%)
/ 0.1 (mm)				TF11: Thickness(Without plating) ± 0.05 (mm) and Flatness 0.08/0.1 (mm)

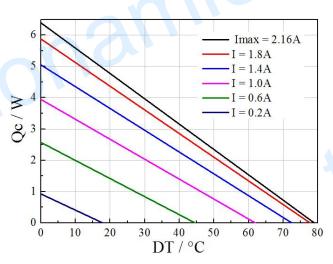
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Performance Specification Sheet

Specification of Thermoelectric Module

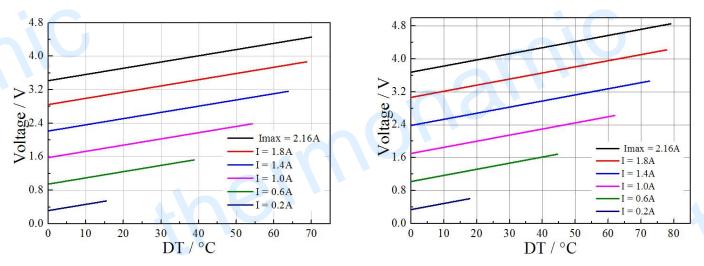
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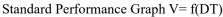


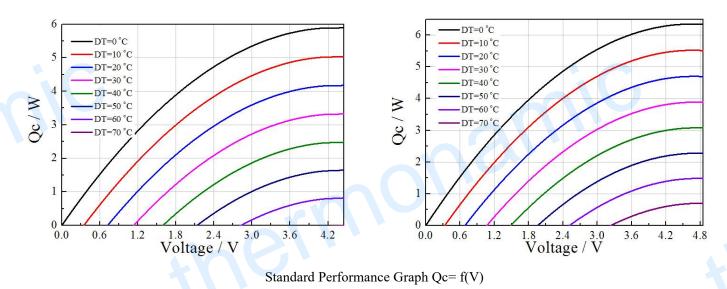


Performance Curves at Th=50 °C

Standard Performance Graph Qc = f(DT)



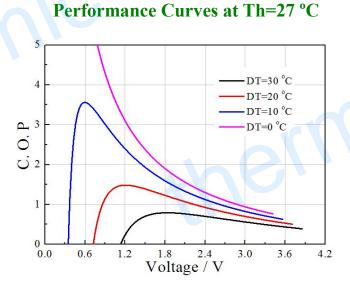


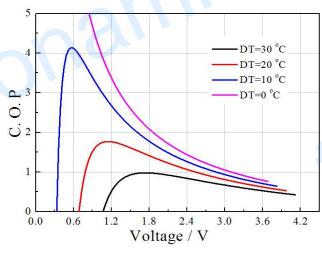


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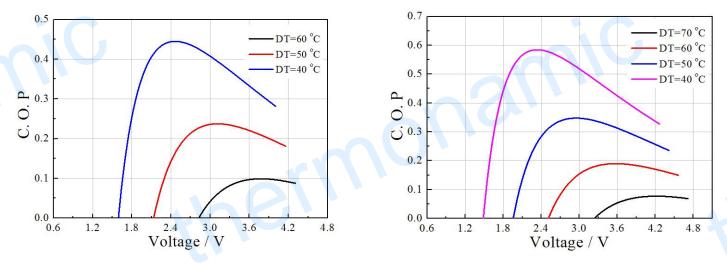
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Performance Curves at Th=50 °C

Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.